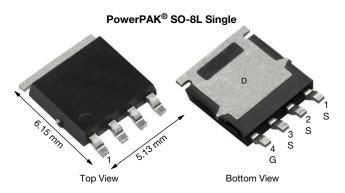
Vishay Siliconix

# Automotive N-Channel 100 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY	
V <sub>DS</sub> (V)	100
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0110
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = 4.5 \text{ V}$	0.0140
I <sub>D</sub> (A)	32
Configuration	Single

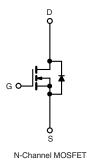
### **FEATURES**

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % R<sub>g</sub> and UIS tested
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>





ROHS COMPLIANT HALOGEN FREE



ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and halogen-free	SQJ402EP (for detailed order number please see <a href="https://www.vishay.com/doc?79771">www.vishay.com/doc?79771</a> )

ABSOLUTE MAXIMUM RATINGS	(T <sub>C</sub> = 25 °C, unles	ss otherwise noted	1)	
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V <sub>DS</sub>	100	V
Gate-source voltage		V <sub>GS</sub>	± 20	V
Continuous drain current <sup>a</sup>	T <sub>C</sub> = 25 °C	1	32	
	T <sub>C</sub> = 125 °C	l <sub>D</sub>	32	
Continuous source current (diode conduction	) a	I <sub>S</sub>	32	Α
Pulsed drain current <sup>b</sup>		I <sub>DM</sub>	75	
Single pulse avalanche current		I <sub>AS</sub>	31	
Single pulse avalanche energy	L = 0.1 mH	E <sub>AS</sub>	48	mJ
	T <sub>C</sub> = 25 °C	D	83	W
Maximum power dissipation	num power dissipation $T_C = 125 ^{\circ}C$ $P_D$ 27	۷V		
Operating junction and storage temperature r	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	
Soldering recommendations (peak temperatu	re) <sup>d</sup>	-	260	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient	PCB mount c	$R_{thJA}$	65	°C/W
Junction-to-case (drain)		$R_{thJC}$	1.8	G/ VV

### Notes

- a. Package limited
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %
- c. When mounted on 1" square PCB (FR-4 material)
- d. See solder profile (<a href="www.vishay.com/doc?73257">www.vishay.com/doc?73257</a>). The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection



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PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static						ı		
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		100	-	-	V	
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.5	2.0	2.5	V	
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA	
		$V_{GS} = 0 V$	V <sub>DS</sub> = 100 V	-	-	1		
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 100 V, T <sub>J</sub> = 125 °C	-	-	50	μΑ	
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 100 V, T <sub>J</sub> = 175 °C	-	-	150		
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	30	-	-	Α	
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10.7 A	-	0.0090	0.0110	1	
Drain acuras an atata registance 3	D	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10.7 A, T <sub>J</sub> = 125 °C	-	-	0.0170		
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 10.7 A, T <sub>J</sub> = 175 °C	-	-	0.0210		Ω
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 9.5 A	-	0.0115	0.0140		
Forward transconductance b	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10.7 A		-	54	-	S	
Dynamic <sup>b</sup>								
Input capacitance	C <sub>iss</sub>			-	1829	2286		
Output capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	-	722	903	pF	
Reverse transfer capacitance	C <sub>rss</sub>		62	78	1 .			
Total gate charge <sup>c</sup>	Qg			-	34	51		
Gate-source charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 50 \text{ V}, I_{D} = 10 \text{ A}$	-	6	-	nC	
Gate-drain charge <sup>c</sup>	Q <sub>gd</sub>	1		-	13	-		
Gate resistance	$R_g$	f = 1 MHz		0.65	1.39	2	Ω	
Turn-on delay time <sup>c</sup>	t <sub>d(on)</sub>				10	15	- ns	
Rise time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, R_L = 5 \Omega$ $I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		-	10	15		
Turn-off delay time <sup>c</sup>	t <sub>d(off)</sub>			-	27	40		
Fall time <sup>c</sup>	t <sub>f</sub>			-	7	11		
Source-Drain Diode Ratings and Char	acteristics <sup>b</sup>	•			•			
Pulsed current <sup>a</sup>	I <sub>SM</sub>			-	-	75	Α	
Forward voltage	$V_{SD}$	I <sub>F</sub> :	= 7 A, V <sub>GS</sub> = 0 V	-	0.77	1.2	V	

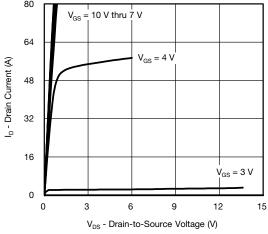
### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

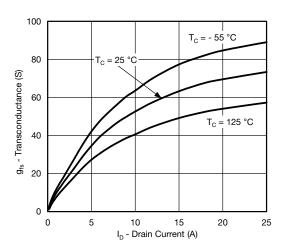
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



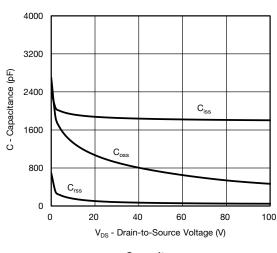
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



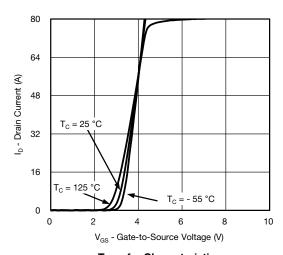
### **Output Characteristics**



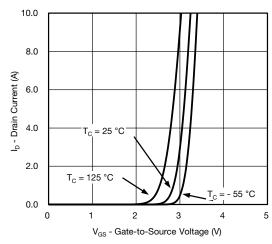
### Transconductance



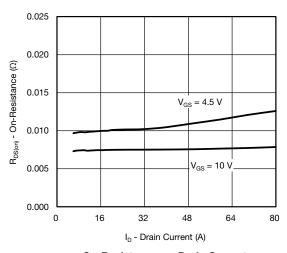
Capacitance



**Transfer Characteristics** 



**Transfer Characteristics** 

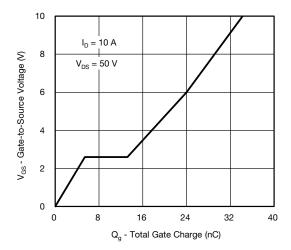


On-Resistance vs. Drain Current

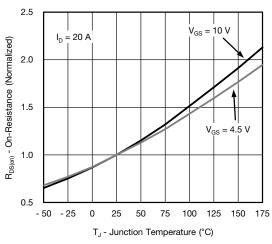
For technical questions, contact: automostechsu



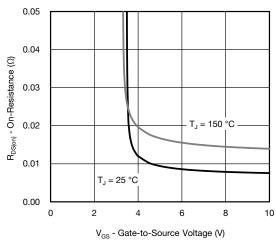
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



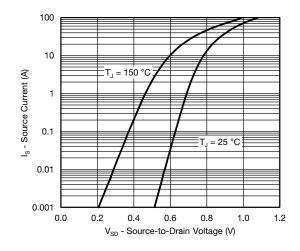
### **Gate Charge**



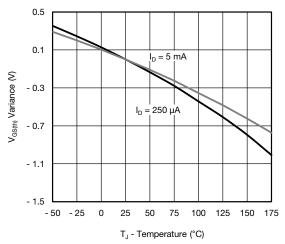
On-Resistance vs. Junction Temperature



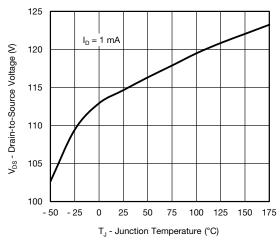
On-Resistance vs. Gate-to-Source Voltage



**Source Drain Diode Forward Voltage** 



Threshold Voltage

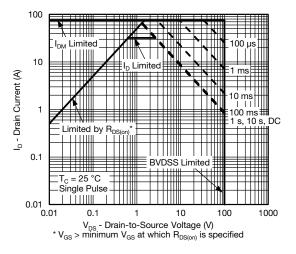


**Drain Source Breakdown vs. Junction Temperature** 

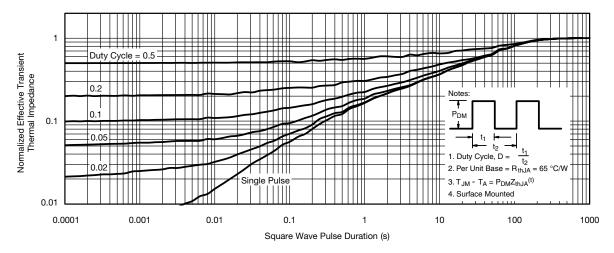
For technical questions, contact: automostechsu



## THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)

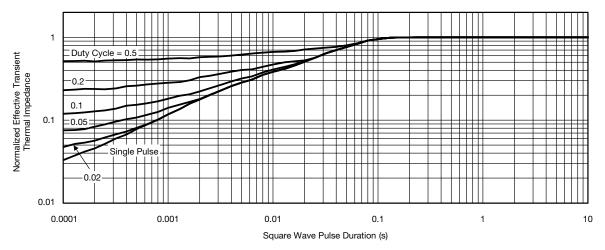


### Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient

## THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- The characteristics shown in the two graphs
  - Normalized transient thermal impedance junction-to-ambient (25 °C)
  - Normalized transient thermal impedance junction-to-case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?67997.



# PowerPAK® SO-8L Case Outline 2



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DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX	
Α	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094			0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
Е	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	2.75	2.85	2.95	0.108	0.112	0.116	
E3	6.05	6.22	6.40	0.238	0.245	0.252	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K		0.51		0.020			
W	0.23			0.009			
W1		0.41			0.016		
W2	2.82		0.111				
W3		2.96			0.117		
θ	0°	-	10°	0°	-	10°	

DWG: 6044

### Note

• Millimeters will govern



### RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



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